

QUADRUPLE OPERATIONAL AMPLIFIER

FEATURES

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.
- ESD Protection <500 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model C = 200 pF, R = 0); 1500 V Using Charged Device Model
- ESD Human Body Model >2 kV Machine Model >200 V and Charge Device Model = 2 kV For K-Suffix Devices.
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.8 mA Typ
- Low Input Bias and Offset Parameters:
 - Input Offset Voltage . . . 3 mV Typ
 - Input Offset Current . . . 2 nA Typ
 - Input Bias Current . . . 20 nA Typ

- Common-Mode Input Voltage Range Includes Ground, Allowing Direct Sensing Near Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage:
 - Non-V devices . . . 26 V
 - V-Suffix devices . . . 32 V
- V-Suffix devices . . . 32 V D Open-Loop Differential Voltage Amplification . . . 100 V/mV Typ
- Internal Frequency Compensation

D OR PW PACKAGE (TOP VIEW) **10UT** 14**∏**40UT 13 🛮 4IN-1IN− **П**2 1IN+ **∏**3 12**∏**4IN+ 11 **∏** GND V_{CC} 10 3IN+ 2IN+ П5 2IN− ¶6 9**∏**3IN– 2OUT 8**∏**30UT

DESCRIPTION

This device consists of four independent high-gain frequency-compensated operational amplifiers that are designed specifically to operate from a single supply over a wide range of voltages. Operation from split supplies is possible when the difference between the two supplies is 3 V to 26 V (3 V to 32 V for V-suffixed devices) and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. The low supply-current drain is independent of the magnitude of the supply voltage.

Applications include transducer amplifiers, dc amplification blocks, and all the conventional operational-amplifier circuits that now can be more easily implemented in single-supply voltage systems. For example, the LM2902 can be operated directly from the standard 5-V supply that is used in digital systems and easily provides the required interface electronics without requiring additional ± 15 -V supplies.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

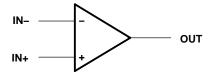


ORDERING INFORMATION

T _A	V _{IO} max AT 25°C	MAX V _{CC}	PAC	CKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	7 mV	26 V	SOIC (D)	Reel of 2500	LM2902QDREP ⁽²⁾	2902EP
	7 1110	20 V	TSSOP(PW)	Reel of 2500	LM2902QPWREP ⁽²⁾	2902EP
–40°C to 125°C	7 mV	32 V	SOIC (D)	Reel of 2500	LM2902KVQDREP ⁽²⁾	2902KVE
-40°C to 125°C	7 mv	32 V	TSSOP(PW)	Reel of 2500	LM2902KVQPWREP ⁽²⁾	2902KVE
	3 mV	32 V	SOIC (D)	Reel of 2500	LM2902KAVQDREP ⁽²⁾	LM2902E
			TSSOP(PW)	Reel of 2500	LM2902KAVQPWREP	LM2902E
	7 mV	26.1/	SOIC (D)	Reel of 2500	LM2902MDREP ⁽²⁾	2902ME
		26 V	TSSOP(PW)	Reel of 2000	LM2902MPWREP ⁽²⁾	2902ME
–55°C to 125°C	7>/	20.1/	SOIC (D)	Reel of 2500	LM2902KVMDREP(2)	2902KME
	7 mV	32 V	TSSOP(PW)	Reel of 2000	LM2902KVMPWREP ⁽²⁾	2902KME
	2 m)/	22.1/	SOIC (D)	Reel of 2500	LM2902KAVMDREP ⁽²⁾	2902KAE
	3 mV	32 V	TSSOP(PW)	Reel of 2000	LM2902KAVMPWREP (2)	2902KAE

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

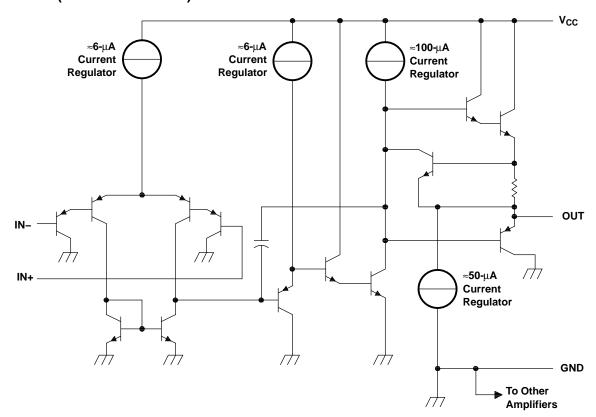
SYMBOL (EACH AMPLIFIER)



⁽²⁾ Product Preview



SCHEMATIC (EACH AMPLIFIER)



COMPONENT COUNT (TOTAL DEVICE)					
Epi-FET	1				
Transistors	95				
Diodes	4				
Resistors	11				
Capacitors	4				



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)(1)

			LM2902-EP	LM2902KV-EP	UNIT
V_{CC}	Supply voltage ⁽²⁾		26	32	V
V_{ID}	Differential input voltage (3)	±26	±32	V	
VI	Input voltage (either input)	-0.3 to 26	-0.3 to 32	V	
	Duration of output short circuit (one amplifier) to group $V_{CC} \le 15 \ V^{(4)}$	Unlimited	Unlimited		
0	Package thermal impedance ⁽⁵⁾⁽⁶⁾	D package (0 LFPM)	101	101	°C/W
θ_{JA}	rackage thermal impedance on the same and th	PW package	113	113	C/VV
T_{J}	Operating virtual junction temperature	142	142	°C	
T _{stg}	Storage temperature range ⁽⁷⁾	-65 to 150	-65 to 150	°C	

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- All voltage values, except differential voltages and V_{CC} specified for the measurement of I_{OS}, are with respect to the network GND.
- (3) Differential voltages are at IN+ with respect to IN-.
- (4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
 (5) Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θJ_A. Operating at the absolute maximum T_J of 142°C can affect reliability.
- The package thermal impedance is calculated in accordance with JESD 51-7.
- (7) Long term high-temperature storage and/or extended use at maximum recommended operating conditions may result in reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.



ELECTRICAL CHARACTERISTICS

at specified free-air temperature, $V_{\rm CC}$ = 5 V (unless otherwise noted)

	DADAMETER	TEST CONDITIONS(1)	T _A ⁽²⁾	LM	2902-EP		LINUT	
	PARAMETER	TEST CONDITIONS ⁽¹⁾		MIN	TYP ⁽³⁾	MAX	UNIT	
V	Input offeet voltege	$V_{CC} = 5 \text{ V to } 26 \text{ V},$	25°C		3	7	mV	
V _{IO}	Input offset voltage	$V_{IC} = V_{ICR} min, V_O = 1.4 V$	Full range			10	mv	
I _{IO}	Input offset current	V _O = 1.4 V	25°C		2	50	nA	
	input onset current	V _O = 1.4 V	Full range			300	ПА	
1	Input bias current	V _O = 1.4 V	25°C		-20	-250	- ^	
I _{IB}	input bias current	V _O = 1.4 V	Full range			-500	nA	
, Common-mode input voltag		V _{CC} = 5 V to 26 V	25°C	0 to V _{CC} - 1.5			V	
V _{ICR} range	range	v _{CC} = 5 v to 26 v	Full range	0 to V _{CC} - 2			V	
		$R_L = 10 \text{ k}\Omega$	25°C	V _{CC} - 1.5				
V_{OH}	OH High-level output voltage	V_{CC} = 26 V, R_L = 2 k Ω	Full range	22			V	
		V_{CC} = 26 V, $R_L \ge 10 \text{ k}\Omega$	25°C	23	24			
V_{OL}	Low-level output voltage	$R_L \le 10 \text{ k}\Omega$	Full range		5	20	mV	
۸	Large-signal differential voltage	$V_{CC} = 15 \text{ V}, V_{O} = 1 \text{ V to } 11 \text{ V},$	25°C		100		V/mV	
A _{VD}	amplification	$R_L \ge 2 k\Omega$	Full range	15				
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$	25°C	50	80		dB	
k _{SVR}	Supply-voltage rejection ratio $(\Delta V_{CC}/\Delta V_{IO})$		25°C	50	100		dB	
V_{O1}/V_{O2}	Crosstalk attenuation	f = 1 kHz to 20 kHz	25°C		120		dB	
		$V_{CC} = 15 \text{ V}, V_{ID} = 1 \text{ V}, V_{O} = 0$	25°C	-20	-30		mA	
		V _{CC} = 15 V, V _{ID} = 1 V, V _O = 0	Full range	-10			ША	
Io	Output current	$V_{CC} = 15 \text{ V}, V_{ID} = -1 \text{ V}, V_{O} = 15 \text{ V}$	25°C	10	20		mA	
		V _{CC} = 13 V, V _{ID} = -1 V, V _O = 13 V	Full range	5			IIIA	
		$V_{ID} = -1 \text{ V}, V_{O} = 200 \text{ mV}$	25°C		30		μΑ	
I _{OS}	Short-circuit output current	V_{CC} at 5 V, $V_O = 0$, GND at -5 V	25°C		±40	±60	mA	
I _{cc}	Supply current (four amplifiers)	V _O = 2.5 V, No load	Full range		0.7	1.2	mA	
'CC	Cupply culterit (lour amplifiers)	$V_{CC} = 26 \text{ V}, V_{O} = 0.5 \text{ V}_{CC}, \text{ No load}$	Full range		1.4	3	шл	

 ⁽¹⁾ All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.
 (2) Full range is -55°C to 125°C.
 (3) All typical values are at T_A = 25°C.



ELECTRICAL CHARACTERISTICS

at specified free-air temperature, $V_{\rm CC}$ = 5 V (unless otherwise noted)

DADAMETED		TEST COMPLETE	ONC(1)	T _A ⁽²⁾	LM2902KV-EP			UNIT	
	PARAMETER	TEST CONDITION	JNS(1)		MIN	TYP ⁽³⁾	MAX	UNII	
			Non-A	25°C		3	7		
\ /	land offertualtees	$V_{CC} = 5 \text{ V to } 32 \text{ V},$	devices	Full range			10	\/	
V_{IO}	Input offset voltage	$V_{IC} = V_{ICR} min, V_O = 1.4 V$	A-suffix	25°C		1	3	mV	
			devices	Full range			4.5		
$\Delta V_{IO}/\Delta T$	Temperature drift	$R_S = 0 \Omega$		Full range		7		μV/°C	
-	land offers and an invest	V _O = 1.4 V		25°C		2	50	Λ	
I _{IO}	Input offset current			Full range			150	nA	
$\Delta V_{IO}/\Delta T$	Temperature drift			Full range		10		pA/°C	
-	lament bing anymout	V _O = 1.4 V		25°C		-20	-250	Λ	
I _{IB}	Input bias current			Full range			-500	nA	
V	Common-mode input voltage	V - 5 V to 22 V		25°C	0 to V _{CC} - 1.5				
V _{ICR} range	V _{CC} = 5 V to 32 V		Full range	0 to V _{CC} - 2			V		
		$R_L = 10 \text{ k}\Omega$	25°C	V _{CC} - 1.5					
V _{OH} High-level output vol	High-level output voltage	$V_{CC} = 32 \text{ V},$	$R_L = 2 k\Omega$	Full range	26			V	
		V _{CC} = 32 V,	R _L ≥ 10 kΩ	Full range	27				
V _{OL}	Low-level output voltage	$R_L = 10 \text{ k}\Omega$		Full range		5	20	mV	
Large-signal differential		$V_{CC} = 15 \text{ V}, V_{O} = 1 \text{ V to } 11 \text{ V},$		25°C	25	100		\//m\/	
A _{VD}	voltage amplification	$R_L \ge 2 k\Omega$		Full range	15			V/mV	
	Amplifier-to-amplifier coupling (4)	f = 1 kHz to 20 kHz, inp	ut referred	25°C		120		dB	
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$		25°C	60	80		dB	
k _{SVR}	Supply-voltage rejection ratio $(\Delta V_{CC} / \Delta V_{IO})$			25°C	60	100		dB	
V _{O1} / V _{O2}	Crosstalk attenuation	f = 1 kHz to 20 kHz		25°C		120		dB	
		$V_{CC} = 15, V_{ID} = 1 V,$		25°C	-20	-30		Λ	
				Full range	-10			mA	
Io	Output current	$V_{CC} = 15 \text{ V}, V_{ID} = -1 \text{ V},$	V _O = 15 V	25°C	10	20		Δ	
10	Output current			Full range	5			mA	
		V _{ID} = -1 V,	V _O = 200 mV	25°C	12	40		μΑ	
I _{OS}	Short-circuit output current	V _{CC} at 5 V, GND at –5 V	$V_0 = 0,$	25°C		±40	±60	mA	
	0	V _O = 2.5 V,	No load	Full range		0.7	1.2		
I _{CC}	Supply current (four amplifiers)	$V_{CC} = 32 \text{ V},$ $V_{O} = 0.5 \text{ V}_{CC},$	No load	Full range		1.4	3	mA	

 ⁽¹⁾ All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.
 (2) Full range is -55°C to 125°C.
 (3) All typical values are at T_A = 25°C.
 (4) Due to proximity of external components, ensure that coupling is not originating via stray capacitance between these external parts. Typically, this can be detected, as this type of coupling increases at higher frequencies.



OPERATING CONDITIONS

 $V_{CC} = \pm 15 \text{ V}, T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain	$R_L = 1 \text{ M}\Omega$, $C_L = 30 \text{ pF}$, $V_I = \pm 10 \text{ V}$ (see Figure 1)	0.5	V/μs
B ₁	Unity-gain bandwidth	$R_L = 1 \text{ M}\Omega$, $C_L = 20 \text{ pF (see Figure 1)}$	1.2	MHz
V _n	Equivalent input noise voltage	$R_S = 100 \Omega$, $V_I = 0 V$, $f = 1 kHz$ (see Figure 2)	35	nV/√ Hz

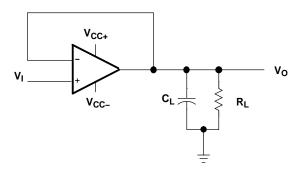


Figure 1. Unity-Gain Amplifier

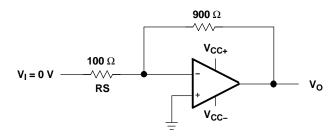


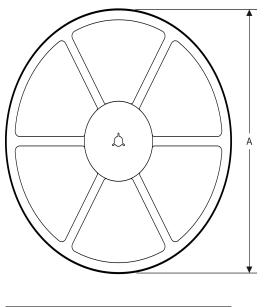
Figure 2. Noise-Test Circuit

PACKAGE MATERIALS INFORMATION

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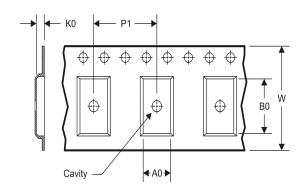
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2902KAVMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KAVQPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2902KAVMPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KAVQPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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